Call for Papers

IMAPS Nordic, in collaboration with IEEE EPS and IMAPS Europe, hereby invite you to submit an abstract to **the 23rd European Microelectronics and Packaging Conference and Exhibition (EMPC2021)**.

EMPC2021 will take place in the beautiful city of **Gothenburg**, Sweden on the **13th to 16th of September 2021**. The event will present the best of microelectronics packaging and interconnection technologies, providing world class coverage of technological innovation in the microelectronics and packaging field with contributions from both industry and academia.

Topics

You are welcome to submit abstract(s) presenting new developments and knowledge in areas such as:

Advanced Packaging
- 3D integration, System-in Packages, FI- and FO-WLP, innovative interconnects, circuit solutions, Panel level packaging, Substrate and Interposer Technologies, emerging Heterogenous Integration Technologies

Advanced packaging for MEMS & sensors
- Sensors, actuators and RF systems

Electronics Reliability & Quality
- Methodology, Predictive maintenance, Novel reliability test methods., Modelling, Statistical reliability analysis and life models, Failure analysis and material characterization

Green Technologies
- Recycling, supply chain, low power computing

Harsh environment applications
- Aerospace, automotive, rail, washable wearables, smart farming, drilling, HTHP (high temperature and high pressure) O&G wells, geothermal energy and process industry

Materials & Processes
- Manufacturing and assembly technologies, new materials, compatibility, enabling materials, nano-materials and processes

Medical electronics
- Implantable devices, miniaturization, neural interfaces, validation, new trends, reliability of implanted electronics, sensors for (implantable) medical devices

Opto-electronics
- Packaging, light sources, detectors, photonic integrated circuits based on III-V/Si technology platforms, emerging materials, applications

Power electronics
- Packaging, Thermal management, Wide Bandgap applications, Energy-conversion technologies,

Printed electronics
- Materials and processes, Flexible, Structural, Applications (automotive, energy, medical, wearable and others)

How to submit

We kindly ask you to start preparing your abstract. The abstract should be 300-500 words and may include images. First, create your profile at www.empc2021.org and follow the instructions for submitting the abstract. The site will be open for submission in September 2020.

Abstract deadline:	Tuesday, January 19th, 2021.
Notification of acceptance:	Tuesday, April 13th, 2021
Full manuscript submission:	Tuesday, June 15th, 2021

We hope to see you in Gothenburg in September 2021!